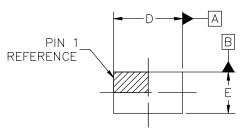


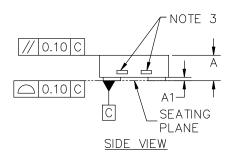


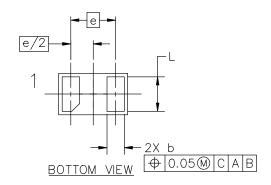
X2DFN2 1.00x0.60x0.37, 0.65P CASE 714AB ISSUE C

DATE 21 FEB 2024



TOP VIEW

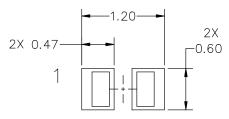




NOTES:

- DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
- 2. ALL DIMENSION ARE IN MILLIMETERS.
- 3. EXPOSED COPPER ALLOWED AS SHOW.

DIM	MILLIMETERS			
	MIN.	NOM.	MAX.	
А	0.34	0.37	0.40	
A1		0.03	0.050	
b	0.20	0.25	0.30	
D	0.95	1.00	1.05	
E	0.55	0.60	0.65	
е	0.65 BSC			
L	0.45	0.50	0.55	



RECOMMENDED MOUNTING FOOTPRINT*

* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XX = Specific Device Code M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " *", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	X2DFN2 1.00x0.60x0.37, 0.	65P	PAGE 1 OF 1	

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